

Harvatek Surface Mount CHIP LEDs Approval Sheet Model No.: HT-F118NB

Acknowledged by

Section Manager

Production Engineering Dept.

Manager

Production Engineering Dept.

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	********	********		HDS-F118-K037
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		2003/12/8	Version of 1.0	Page 1/12



INTRODUCTION	3
PRODUCT SPECIFICATION	4
ATTENTION: ELECTRICSTATIC DISCHARGE (ESD) PROTECTION	4
LABEL SPEC.:	5
PRODUCT FEATURE	7
ELECTRO-OPTICAL CHARACTERISTICSPACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR REFLOW SOLDERING	
ABSOLUTE MAXIMUM RATINGS	7
PACKAGING TAPE, REEL, AND PACKING MODEL	9
TAPE DIMENSION	9
DRY PACK	10
CAUTIONS OF PICK AND PLACE	11
PRECAUTIONS	11
SOLDERING PATTERN	11
REFLOW SOLDERING	12
CLEANINGCAUTIONS OF PICK AND PLACE	

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	********	*******		HDS-F118-K037
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		2003/12/8	Version of 1.0	Page 2/12



Introduction

- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by HARVATEK for any infringements of intellectual property or other rights of the third parties which may result from it use.
- Harvatek is continually effort to improve the quality of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing HARVATEK products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such HARATEK products cause loss of human life, bodily injury or damage to property.
- The HARVATEK products listed in this document are intended for usage in general electronics (computer, personal equipment, office equipment, industrial robotics, domestic, etc...) These products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury.
- In developing your designs, please ensure that HARVATEK products are used within specified operating ranges as set forth in the most recent HARVATEK products specifications.
- Also, please keep in mind the precautions listed in this document.

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	*********	*****		HDS-F118-K037
	ect to changes for improvement Proprietary data, drawings, and ights reserved.	2003/12/8	Version of 1.0	Page 3/12



Product Specification

	Specification	Material	Quantity
lv	90-180mcd		
	@20mA/ Ta= 25 ^o C		
	Tolerance: + 10%		
Wavelength	464-476 nm		
	@20mA/ Ta= 25 ^o C		
Vf	2.7~3.9 (0.2V/1Bin)		
	@20mA/ Ta= 25 ^o C		
Ir	< 100 µA @ V _R = 5 V		
Resin	Milky white	Epoxy resin	
Carrier tape	According to EIA 481-1A specs	Conductive black tape	2000pcs per reel
Reel	According to EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel one bag
Carton	HT standard	Paper	Non-specified

Others:

Every mid-box will be loaded 5 reels. These 5 reels can be different in lot, lv, lambda, or Vf. Every reel will have an independent label to identify its specification and the mid-box there will have a corresponding label post on it.

ATTENTION: Electricstatic Discharge (ESD) protection

The symbol shown on the page herein to introduce 'Electro-Optical

Characteristics'. ESD protection for GaP and AlGaAs based chips is still necessary even though they are safe in low static-electric discharge. Parts built with AlInGaP,

GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD protection has to considered and taken in the initial design stage.

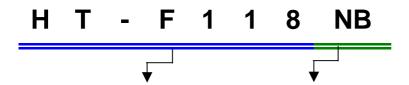
If manual work/process is needed, please ensure the device is well protected from ESD during all the process.

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	*********	*****		HDS-F118-K037
	ect to changes for improvement Proprietary data, drawings, and ights reserved.	2003/12/8	Version of 1.0	Page 4/12



Label Spec.:

Harvatek P/N



Series Name	Emitting Color
HT-F118: 3.2x1.2x0.8mm	NB:
	Blue@20mA

Lot No.

1 2 3 4 5 6 7 8 9 10 P 1 2 2 3 0 A - D T

Code 1	Code 2	Code 3	Code 4, 5	Code 6, 7	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Lots	Resin Color	Packaging
		1: Jan.				
	Z: 2000	2: Feb.				
Internal	1: 2001			04 00	D. Millov White	T. Tonad Book
	2: 2002	9: Sep.	1~31/ (30)	01~99,	D: Milky White	T: Taped Reel
Tracing Code	3: 2003	A: Oct.		A,B,C		
		B: Nov.				
		C: Dec.				

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	******	*******		HDS-F118-K037
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		2003/12/8	Version of 1.0	Page 5/12



Iv Bin:

Color	Bin Code	Spec. Range
Blue	Q2	90-112.5 mcd
	R1	112.5-140 mcd
	R2	140-180 mcd

Color Bin:

Color	Bin Code	Spec. Range
Blue	В	464-468 nm
	С	468-472 nm
	D	472-476 nm

Vf Bin:

Color	Bin Code	Spec. Range	
	G8	2.7-2.9V	
	H7	2.9-3.1V	
Dive	Н8	3.1-3.3V	
Blue	J7	3.3-3.5V	
	J8	3.5-3.7V	
	K7	3.7-3.9V	

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	*********	********		HDS-F118-K037
	ect to changes for improvement Proprietary data, drawings, and rights reserved.	2003/12/8	Version of 1.0	Page 6/12



Product Feature

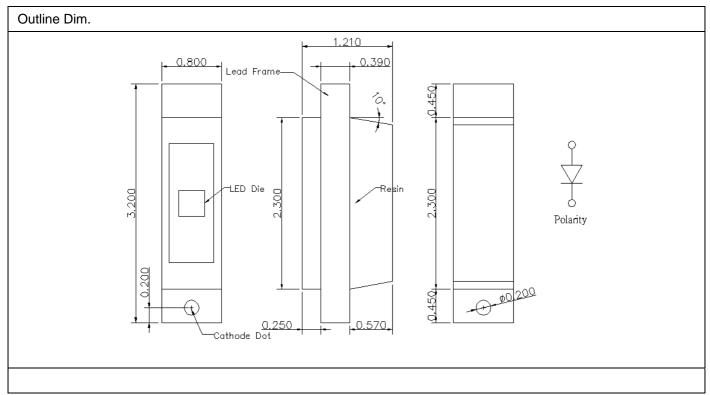
Electro-Optical Characteristics

(IF @ 20mA, Ta 25 °C)

Code for parts Lighting Color		Material	V_{F}	(V)		λ(nm)		I [*] _V (mcd)
Code for parts L	Lighting Color	ivialeriai	typ	max	λ _D	λ_{P}	Δλ	Typical.
HT-F118NB	Blue	InGaN	3.3	3.9	470	468	30	120

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

Unit: mm Tolerance: +/-0.1



Absolute Maximum Ratings

(Ta 25 °C)

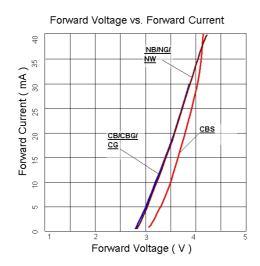
Series	P _d (mW)	I _F (mA)	I _{FP} (mA)	V _R (V)	I _R (uA)	T _{OP} (°C)	T _{ST} (°C)
HT-F118NB	78	20	80**	5	<100@ V _R = 5	-30~+80	-40~+85

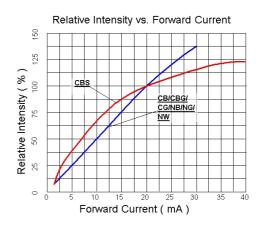
^{**} Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

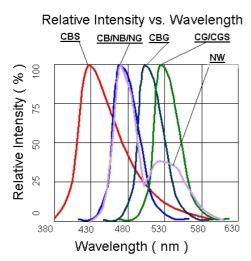
Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	*******	*******		HDS-F118-K037
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		2003/12/8	Version of 1.0	Page 7/12

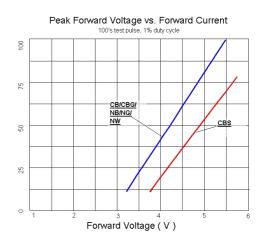


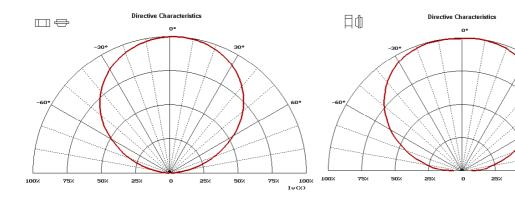
Characteristics of HT-F118 Series







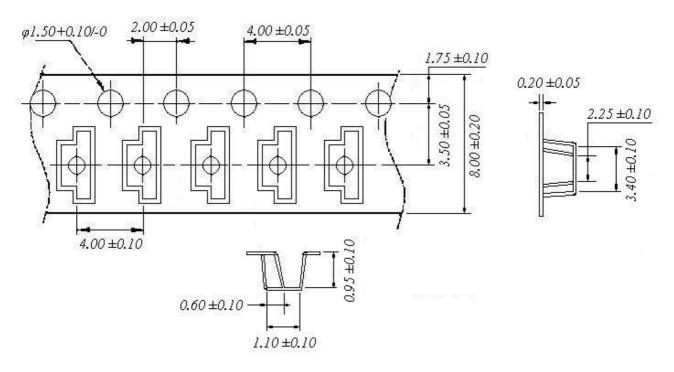




Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	********	*****		HDS-F118-K037
	ect to changes for improvement Proprietary data, drawings, and ights reserved.	2003/12/8	Version of 1.0	Page 8/12

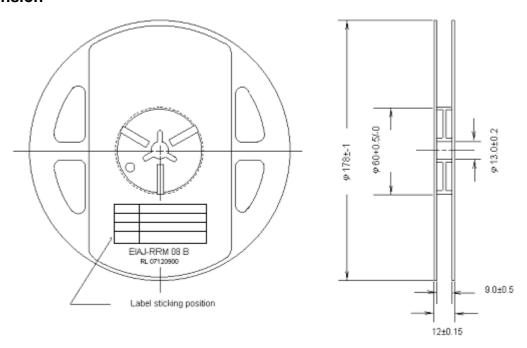


Packaging Tape, Reel, and Packing Model Tape Dimension



Unit: mm Tolerance: + / - 0.1 mm

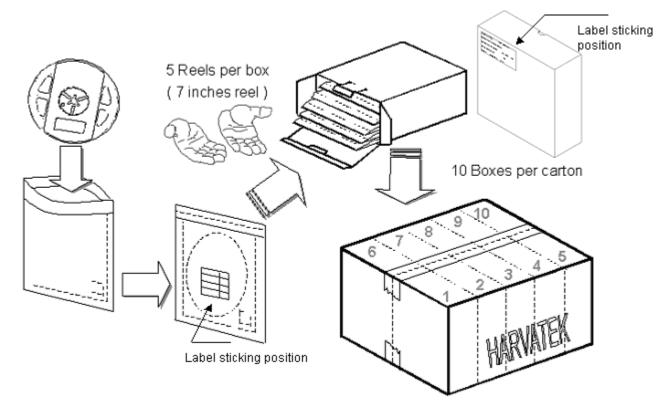
Reel Dimension



Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	********	******		HDS-F118-K037
	ect to changes for improvement Proprietary data, drawings, and ights reserved.	2003/12/8	Version of 1.0	Page 9/12



Packing Model



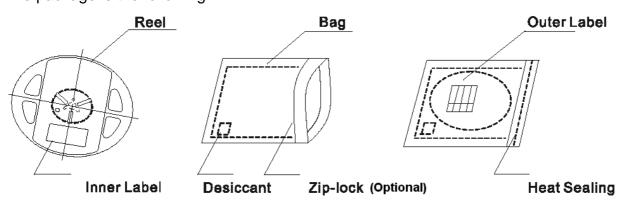
5 boxes per carton is available according to shipping quantity.

Dry Pack

Any SMD optical device, like this chip LED, is **MOISTURE SENSITIVE device**. Avoid absorbing moisture at any time during transportation or storage. Every reel will be packaged in the moisture barrier anti-static bag (Specific bag material will depend upon customers' requirement or option). And the bag is well sealed before shipment.

By customer's requirement, we will put a humidity indicator in each moisture barrier anti-static bag before shipment.

The package is the following:



Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	*********	******		HDS-F118-K037
	ect to changes for improvement Proprietary data, drawings, and ights reserved.	2003/12/8	Version of 1.0	Page 10/12



Cautions of Pick and Place

It should be avoided to load stress on the resin during high temperature.

Avoid rubbing or scraping the resin by any object.

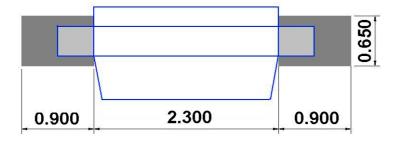
Electric-static may cause damage to the component. Please confirm that the equipment grounding well. Using an ionizer fan is recommended.

PRECAUTIONS

- 1. Avoid absorbing moisture at any time during transportation or storage.
- 2. Anti-Static process is needed especially when handling GaN, InGaN, and AlInGaP products.
- 3. It is suggested to connect the unit with a proper series current limit resistor. Avoid driving reverse voltage over the specification of LEDs when turning the unit ON/OFF.
- 4. Any application should refer to the specifications of absolute maximum ratings.
- 5. Avoid any direct contact with the viewing area.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Soldering pattern

The dimensions of the recommended soldering pattern may not meet every user. Please confirm and study first before designing the soldering pattern in order to obtain the best performance of soldering. Recommended soldering pattern is listed below.



Soldering terminal may shift in x, y direction.

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	*********	********		HDS-F118-K037
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		2003/12/8	Version of 1.0	Page 11/12



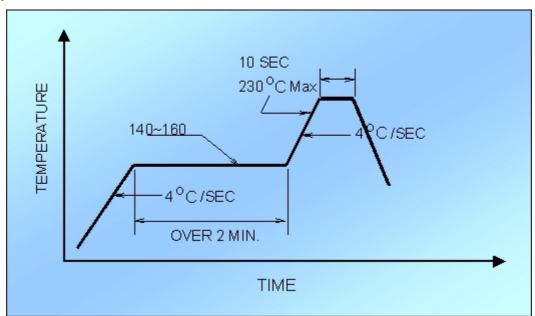
Reflow Soldering

Recommend soldering paste specifications:

Melting temperature: 178~192 °C

Contains: Sn 63%, Pb 37%

Never take next process until the component is cooled down to room temperature after reflow. The recommended reflow soldering profile (measuring on the surface of the LED terminal) is following:



Cleaning

The conditions of cleaning after soldering:

An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.

TemperaturexTime: <50 °Cx30sec, or <30 °Cx3min

Ultra sonic cleaning: < 15W/ bath; Bath volume: 1liter max.

Curing: 100 °C max, <3min

Do not contact with component on the assembly board.

Cautions of Pick and Place

It should be avoided to load stress on the resin during high temperature.

Avoid rubbing or scraping the resin by any object.

Electric-static may cause damage to the component. Please confirm that the equipment grounding well. Using an ionizer fan is recommended.

Official Product	HT Part No. HT-F118NB	Your Part No.		Data Sheet No.
Tentative Product	*******	********		HDS-F118-K037
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		2003/12/8	Version of 1.0	Page 12/12